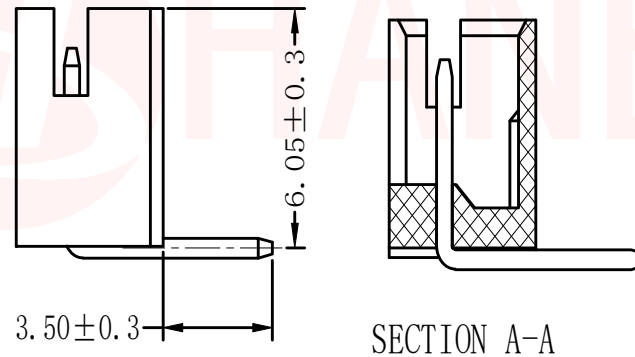
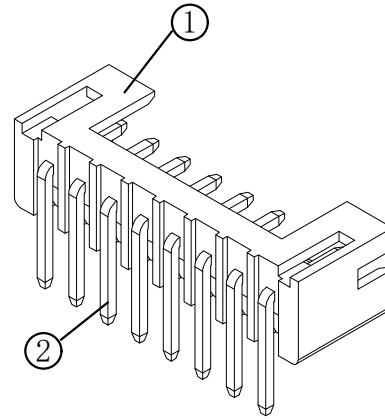
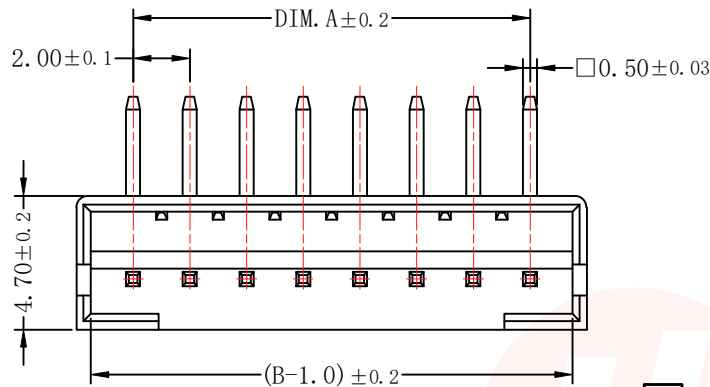
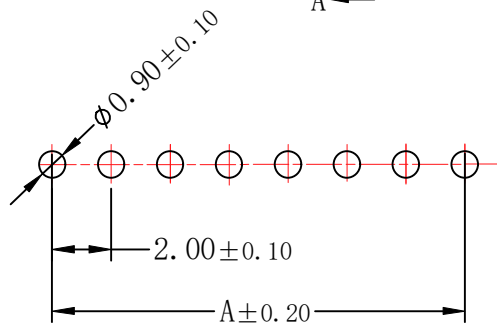
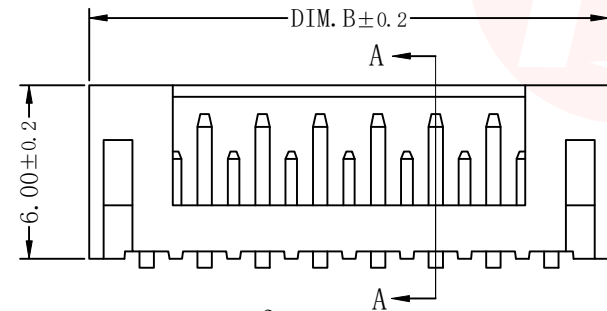




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



SECTION A-A



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

- 1、塑件材料: PA66 (UL-94V-0)
- 2、接触件: 黄铜镀锡
- 3、接触电阻: $\leq 10m\Omega$
- 4、绝缘电阻: $\geq 1000M\Omega$
- 5、额定电压: 250V AC DC
- 6、额定电流: 2.0A AC DC
- 7、耐压: 能承受1000V AC/Minute
- 8、工作温度: $-25^{\circ}\sim+85^{\circ}$
- 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度 235^{+5}_{-0} , 时间 2.5 ± 0.5 秒
- 10、铅和镉等六大有害物质含量要符合环保要求

TABLE:

CSG PART NO.	Dimension mm		
	PIN	A	B
WAFER-PH200WZ-2A	2P	2.00	6.00
WAFER-PH200WZ-3A	3P	4.00	8.00
WAFER-PH200WZ-4A	4P	6.00	10.00
WAFER-PH200WZ-5A	5P	8.00	12.00
WAFER-PH200WZ-6A	6P	10.00	14.00
WAFER-PH200WZ-7A	7P	12.00	16.00
WAFER-PH200WZ-8A	8P	14.00	18.00
WAFER-PH200WZ-9A	9P	16.00	20.00
WAFER-PH200WZ-10A	10P	18.00	22.00
WAFER-PH200WZ-11A	11P	20.00	24.00
WAFER-PH200WZ-12A	12P	22.00	26.00
WAFER-PH200WZ-20A	20P	38.00	44.00

序号	名称	材料	电镀(锡): 整个表面镀底锡	
1	端子/Contact	黄铜	30U"MIN 再镀锡80U" MIN	
2	基座/Wafer	PA66 (UL94V-0)	白色	
UNLESS OTHERWISE SPECIFIED TOLERANCES			东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS: ANGLES:				
X	:±0.20	X		:±2°
X.X	:±0.10	X.X		:±1°
X.XX	:±0.05			
TITLE	WAFER PH 2.00MM 弯针 DIP TYPE			
DWN	xiong	PART NO. WAFER-PH200WZ-NA		
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:10F 1	
REV: A4				
CUSTOMER COPY				